

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:	William Planey	Confirmation No.:	9343
Serial No.:	10/728,449	Art Unit:	2818
Filed:	December 5, 2003	Examiner:	Nguyen, Dao H.
For:	Flip-Chip Packaging	Attorney Docket No:	65860-5001-US (Formerly LOVE-51.CON)

STATEMENT UNDER 37 C.F.R. § 3.73(b)

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450


Sir:

Lovoltech Inc., a corporation, states that it is the assignee of the entire right, title and interest in the patent application identified above by virtue of an assignment from the inventor(s) of the parent of the patent application identified above.

The assignment was recorded in the United States Patent and Trademark Office on December 9, 2003 at Reel 014772, Frame 0206.

The undersigned is authorized to act on behalf of the assignee.

Date: October 5, 2006

  
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